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SJ

INDUSTRY STANDARD OF THE PEOPLE'S REPUBLIC OF CHINA

SJ/Z 21356-2018

Design guidelines for flip chip bonding process of SiP products

SiP 产品芯片倒装工艺设计指南

(English Translation)

Issued by: Ministry of Industry and Information Technology

Preview: page 1 of 3 shown, 11 in the full document. Complete English PDF, instant download:
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Table of Contents

[Preview only]
1 Scope
2 Normative References
2.1 Terms
3 Terms and Definitions
4 Overview
4.1 General requirements
5 Technical Requirements
6 Calibration conditions
6.1 Environmental conditions
6.2 Measurement standards and other equipment
7 Calibration items and calibration methods
7.1 Calibration Items
7.2 Calibration method
8 Expression of calibration results
9 Recalibration interval

1 Foreword

SJ/Z 21356-2018 was issued by Ministry of Industry and Information Technology on 18 January 2018.

The SJ/Z prefix marks a guiding technical document.

The document runs to 11 pages in English translation.

2 Scope Preview

SJ/Z 21356-2018 is filed under Chinese Standard Classification L55, in the field of electronic components and information technology.

This catalogue holds 369 other SJ/Z standards without an ICS number.

In this catalogue, SJ/Z standards carry edition years from 1973 to 2025.

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https://chinastandards.org/standards/sj-z-21356-2018

3 About this standard

Sector: Electronics Industry Standard

Issued by: Ministry of Industry and Information Technology

English translation: about 11 pages (approximate)

Chinese original: about 16,151 characters

4 Related standards

Standards on related subjects:

GB/T 46280.2-2025 - Specification for chiplet interconnection interface - Part 2: Protocol layer technical requirements

SJ/T 11891-2023 - Energy efficiency measurement method for LED displays

GB/T 35010.6-2018 - Semiconductor die products -- Part 6: Requirements for concerning thermal simulation

SJ/Z 21357-2018 - Design guidelines for chip stacking process of SiP products

SJ/Z 21355-2018 - Design guidelines for hermetic package of SiP products

SJ/Z 21354-2018 - Design guidelines for assemblability of SiP products

5 Classification and status

Chinese Standard Classification (CCS): L 55

Prefix SJ/Z: guiding technical document.

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